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At page 5, lines 20-21:

-- Figure 1A gives a symbolic representation of a syndiotactic configuration of a polymer.

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Figure 1B gives a symbolic representation of an isotactic configuration of a polymer.

Figure 1C gives a symbolic representation of an atactic configuration of a polymer. --

IN THE CLAIMS

Please cancel Claims 11, 12, 31, 32, 58, and 59, and replace Claims 1, 21, 42, 43, and 48 with the following amended Claims 1, 21, 42, 43, and 48:

(Amended) A laminated structure comprising:

a non-woven substrate;

at least one elastic strand; and

a hot-melt adhesive composition bonding the non-woven substrate and the at least one elastic strand to one another, wherein the adhesive composition includes between about 50 and about 90 weight percent atactic polypropylene having a degree of crystallinity of less than about 20% and a number-average molecular weight between about 500 and about 40,000, and between about 5 and about 50 weight percent isotactic polypropylene having a degree of crystallinity of at least about 40% and a number-average molecular weight between about 3,000 and about 150,000, wherein the adhesive composition has a melt index between about 200 and about 1800 grams per 10 minutes and is hot-melt processable at less than about 450 degrees Fahrenheit.

21. (Amended) A laminated structure comprising:

a first non-woven elastic substrate;

a second non-woven substrate; and

a hot-melt adhesive composition bonding the first non-woven elastic substrate and the second non-woven substrate to one another, wherein the adhesive

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composition includes between about 50 and about 90 weight percent atactic polypropylene having a degree of crystallinity of less than about 20% and a number-average molecular weight between about 500 and about 40,000, and between about 5 and about 50 weight percent isotactic polypropylene having a degree of crystallinity of at least about 40% and a number-average molecular weight between about 3,000 and about 150,000, wherein the adhesive composition has a melt index between about 200 and about 1800 grams per 10 minutes and is hot-melt processable at less than about 450 degrees Fahrenheit.

- 42. (Amended) The laminated structure of Claim 21, wherein the first elastic substrate comprises at least one of the group consisting of a necked-bonded laminate, a stretch-bonded laminate, a polypropylene spunbonded layer, a polyethylene layer in combination with a polypropylene spunbonded layer, a styrene-isoprene-styrene strand, a styrene-butadiene-styrene strand, a styrene-ethylene/propylene-styrene strand, a styrene/ethylene-co-butadiene/styrene strand, and a polyurethane strand.
- 43. (Amended) The laminated structure of Claim 21, wherein the second substrate comprises at least one of the group consisting of a necked-bonded laminate, a stretch-bonded laminate, a spunbond-meltblown-spunbond laminate, a polypropylene spunbonded layer, a polyethylene layer in combination with a polypropylene spunbonded layer, a styrene-isoprene-styrene strand, a styrene-butadiene-styrene strand, a styrene-ethylene/propylene-styrene strand, a styrene/ethylene-co-butadiene/styrene strand, and a polyurethane strand.
 - 48. (Amended) An absorbent article comprising:
 - a first elastomeric substrate;
 - a second substrate; and
- a hot-melt adhesive composition bonding the first substrate and the second substrate to one another, wherein the adhesive composition includes between about 50 and about 90 weight percent of an atactic polypropylene having a degree of

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